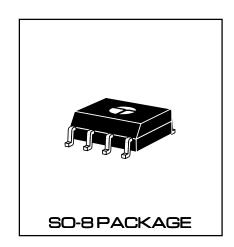


ULTRA LOW CAPACITANCE TVS ARRAY

APPLICATIONS

- ✓ Hand Held Electronics
- ✓ Sense & Control Circuits
- ✓ FireWire
- ✓ Ethernet 10/100 Base T



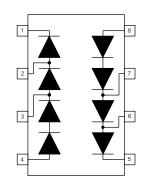
IEC COMPATIBILITY (EN61000-4)

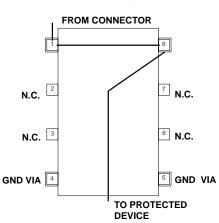
- √ 61000-4-2 (ESD): Air 15kv, Contact 8kv
- ✓ 61000-4-4 (EFT): 40A 5/50ns

FEATURES

- ✓ Suitable for Low Capacitance High Speed V²D Protection
- ✓ 500 Watts Peak Pulse Power Dissipation per Line (8/20 µs)
- ✓ Bidirectional Configuration
- ✓ ESD Protection > 40 kilovolts
- ✓ Ultra Low Capacitance < 1.25 pF @ 0V, 1 MHz</p>
- ✓ Standard SO-8 Package
- ✓ Low Clamping Voltage < 5 Volts
 </p>
- ✓ UL 94V-0 Flammability Classification

CIRCUIT DIAGRAM & PCB LAYOUT RECOMMENDATION





1.0

DEVICE CHARACTERISTICS

MECHA	NIC	AL C	HARACTE	ERISTICS	MAXIMUMRATINGS						
PACKAGE PACKAGING APPROX. WEIGHT DEVICE MARKINGS MISCELLANEOUS		Molded SO-8 Surface Mount 12 mm Tape per EIA 481-1 0.1 grams Logo & Marking Code Pin 1 Indicated by Dot on Top of Package			OPERATING REPETITIO T _{CLAMPING}	P _{PP} @ 25°C (SEE FIGURE 1) OPERATING & STORAGE TEMPERATURE REPETITION RATE (DUTY CYCLE) T _{CLAMPING} (0 VOLTS TO V _(BR) MIN.)			500 Watts, 8/20 μs Waveshape -55° to +150°C 0.01% Bidirectional: < 1 x 10 ⁻⁹ seconds		
ELECTRICAL CHARACTERISTICS @ 25°C Ambient Temperature											
PROTEK PART NUMBER	MAI	EVICE RKING ODE	RATED STAND-OFF VOLTAGE V _{WM} VOLTS	BREAKDOWN VOLTAGE (NOTE 2) @ 1 mA V _(BR) VOLTS	MAXIMUM REVERSE LEAKAGE CURRENT @ V _{WM} I _D (NOTE 2) μΑ	MAXIMUM CLAMPING VOLTAGE (See Fig. 2) (NOTE 2) @ 8/20 µs V _C @ I _{PP}	WORKING INVERSE BLOCKING VOLTAGE (NOTE 3) V _{WIB} VOLTS	MAXIMUM CAPACITANCE (NOTE 1) @ 0V, 1 MHz C pF	INVERSE BLOCKING LEAKAGE CURRENT @ V _{WIB} I _R (NOTE 3) µA		

20

10.0V @ 50A

75

Note 1: Capacitance from pin 1 to pin 4 < 1.25 pF, capacitance from pin 8 to pin 5 < 1.25pF.

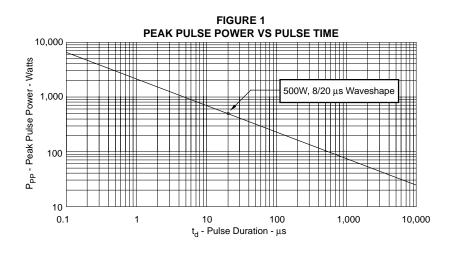
2.5

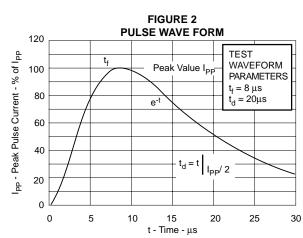
Note 2: Apply positive voltage from pin 4 to pin 1 & pin 8 to pin 5. Note 3: Apply positive voltage from pin 1 to pin 4 & pin 5 to pin 8.

1.0

PLC496

VEC

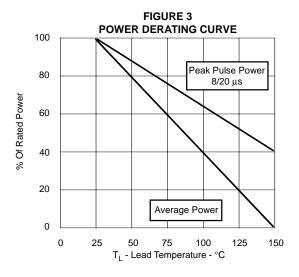


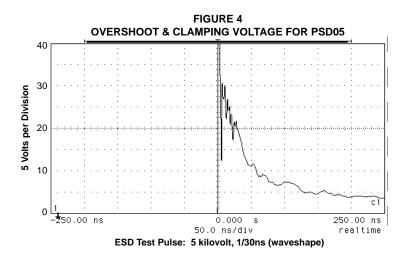


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2 5109.R2 7\01

DEVICE CHARACTERISTICS





DEVICE SPECIFIC APPLICATION NOTE

The PLC496 is an ultra low capacitance, bidirectional, TVS array designed to protect I/O or high-speed data lines from the effects of ESD or EFT. In addition, this series has a surge capability of 500 Watts $P_{\mbox{\footnotesize{PP}}}$ line for an 8/20 $\mu\mbox{\footnotesize{B}}$ waveshape and offers ESD protection > 25kV.

The PLC496 is ideal for use in protecting and maintaining signal integrity in I/O and sensor circuit applications. When a transient occurs, the steering diodes are forward biased, conducting the transient current away from the sensitive circuitry. For most applications, ESD is considered a common mode (line-to-ground) transient event and EFT is considered a differential mode (line-to-line) transient event.

The PLC496 is designed to protect one bidirectional line where the normal signal voltage is both positive and negaitve. Figure 1 shows a typical differential mode (line-to-line) I/O port protection circuit application. Pins 1, 4, 5 and 8 are connected to the data lines. Pins 2, 3, 7 and 6 are not connected.

In addition, the PLC496 can provide protection for sensor circuit applications. Figure 2, a typical common mode (line-to-ground) sensor circuit application, shows pins 1 and 8 of each TVS device connected to the line and pins 4 and 5 connected to ground.

Circuit Board Layout Recommendations

Circuit board layout is critical for Electromagnetic Compatibility (EMC) protection. The following guidelines are recommended:

- ✓ The PLC496 should be placed near the input terminals or connectors. By placing the TVS close to the connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- ✓ The path length between the TVS device and the protected line should be minimized.
- ✓ All conductive loops including power and ground loops should be minimized.
- ✓ The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- ✓ Ground planes should be used whenever possible. Ground vias are recommended for multilayer PCBs.

Figure 1. Typical Differential Mode I/O Port Protection Circuit

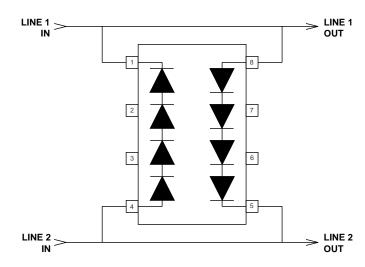
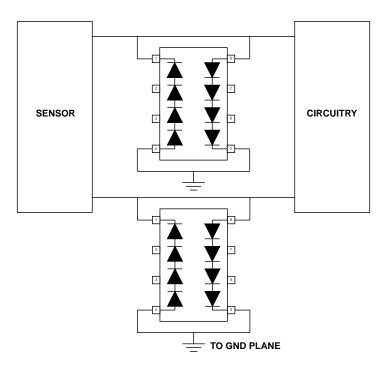


Figure 2. Typical Common-Mode Sensor Protection Circuit





SPICE MODEL & PARAMETERS

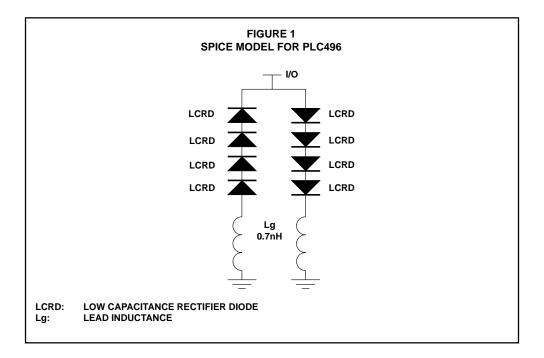
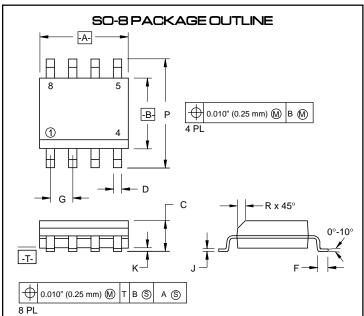
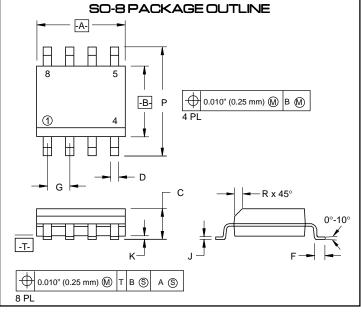
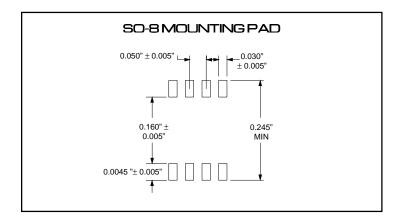


TABLE 1 - SPICE PARAMETERS							
PARAMETER	UNIT	LCRD					
BV IBV Cjo Is	V μA pF A	200 0.01 5 10E ⁻¹⁴					
Vj M N	- -	0.6 0.33 1					
Rs TT EG	Ohms μs eV	0.31 1 1.11					

PACKAGE OUTLINES & DIMENSIONS







SO-8 PACKAGE DIMENSIONS

	MILLIM	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.196	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.250	0.016	0.049	
G	1.27 BSC	1.27 BSC	0.05 BSC	0.05 BSC	
J	0.18	0.25	0.007	0.009	
K	0.10	0.25	0.004	0.008	
Р	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

NOTES:

- T = Seating Plane
 Dimension "A" is Datum.
- 3. Dimension "A" and "B" do not include mold protusion.
- 4. Maximum mold protusion is 0.15" (0.006 mm) per
- 5. Dimensioning and tolerances per ANSI Y14.5M, 1982.

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